Electronic Par							
Application Number:	105	10597136					
Filing Date:	12-	12-Jul-2006					
Title of Invention:	SEI	SEMICONDUCTOR DEVICE MODULE STRUCTURE					
First Named Inventor/Applicant Name:	Kei	Kenji Kitamura					
Filer:	Da	David Spaw/Paula Almasy					
Attorney Docket Number:	SH	SHM-16693					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 I	Filing Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:					1		
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
		1501	1	1510			

Publ. Fee- early, voluntary, or normal

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810